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RECORDATION FORM COVER SHEET TRADEM

U.S. Department of Commerce

		HITA.0547
To the Honoral	ble Commissioner of Patents and Trademarks. Pl	ease record the attached original documents or copy thereof.
 Name of Conveying Party(ies): Fumio OOTSUKA, (2) Yusuke NONAKA, (3) Satoshi SHIMAMOTO, Sohei OMORI and (5) Hideto KAZAMA 		 Name and Address of Receiving Party(ies): Name: Hitachi, Ltd. Address: 6, Kanda Surugadai 4-chome City: Chiyoda-ku, Tokyo, Japan
	• •	
	s of conveying parties attached: Yes No Conveyance:	-
3. Nature of	Conveyance.	
X Assig Secur Other	rity Agreement	
Execution I	Dates: (1)(2)(4)(5) March 4, 2002; (3)	
March 14, 2	2002	
4. (a) Patent	t Application Number(s):	·
10/846,872		4. (b) Patent Numbers:
☐ Additional	Numbers Attached. Address of Party to whom Correspondence	6. Total Number of Applications and Patents Involved: 1
Concerning thi	is Document Should be Mailed:	
Name:	Stanley P. Fisher	7. Total Fee: \$40.00 (37 C.F.R. § 3.41)
Address:	Reed Smith LLP 3110 Fairview Park Dr. Suite 1400 Falls Church, VA. 22042	Enclosed.Authorized to be charged to deposit account.
		8. Deposit Account Number: 08-1480
DO NOT HOT	ETHIC OD A CE	ATTACH DUPLICATE COPY OF THIS PAGE IF PAYING BY DEPOSIT ACCOUNT
DO NOT USE	E THIS SPACE	
9. Statemen	t and Signature:	
To the bes		ue and correct and any attached copy is a true copy of the
-/-	I hada	July 26, 2004
Stanley P. Fish	ner, Registration No. 24, 344	Juan Carlos A. Marquez, Registration No. 34,072
	of pages comprising cover sheet: 1	- 1
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07/28/2004

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PATENT REEL: 015608 FRAME: 0471

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

A SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND A METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner-ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)

(発明者フルネームサイン)

1) Junio O otala (Fumio OOTSUKA) 4/March/2002 2) Junio Punio (Yusuke NONAKA) 4/March/2002

3) Satoshi Shimenote (Satoshi SHIMAMOTO) 14/ March / 2002

(Sohe) Sohei OMORI) 4/ March / 2002

5) Hideto Kazama (Hideto KAZAMA) 4/ March / 2002

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o) ______

PATENT REEL: 015608 FRAME: 0472

Date Signed

(署名日)

RECORDED: 07/26/2004